



## PNP Silicon Small Signal Transistor

**Qualified per MIL-PRF-19500/382**

**Qualified Levels:**  
JAN, JANTX, and  
JANTXV

### DESCRIPTION

This 2N2944AUB through 2N2946AUB PNP silicon transistor device is military qualified up to a JANTXV level for high-reliability applications. Microsemi also offers numerous other products to meet higher and lower power voltage regulation applications.

**Important:** For the latest information, visit our website <http://www.microsemi.com>.

### FEATURES

- Surface mount equivalent of JEDEC registered 2N2944A thru 2N2946A series.
- Low-profile ceramic surface mount package.
- JAN, JANTX, and JANTXV qualification per MIL-PRF-19500/382 available.
- RoHS compliant versions available (commercial grade only).

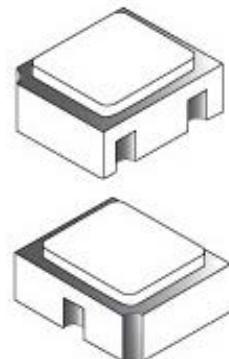
### APPLICATIONS / BENEFITS

- Small lightweight package.
- ESD to Class 3 per MIL-STD-750, method 1020.

### MAXIMUM RATINGS @ +25 °C unless otherwise noted.

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	T <sub>J</sub> and T <sub>STG</sub>	-65 to +200	°C
Thermal Resistance Junction-to-Ambient <sup>(2)</sup>	R <sub>θJA</sub>	435	°C/W
Thermal Resistance surface mount Junction to Solder Point	R <sub>θJSP</sub>	90	°C/W
Collector Current (dc)	I <sub>C</sub>	-100	mA
Emitter to Base voltage (static), collector open	V <sub>EBO</sub>	-15 -25 -40	V
Collector to Base voltage (static), emitter open	V <sub>CBO</sub>	-15 -25 -40	V
Collector to Emitter voltage (static), base open	V <sub>CEO</sub>	-10 -20 -35	V
Emitter to Collector voltage	V <sub>ECO</sub>	-10 -20 -35	V
Total Power Dissipation, all terminals @ T <sub>A</sub> = +25 °C <sup>(1)</sup>	P <sub>T</sub>	400	mW
Total Power Dissipation, all terminals @ T <sub>SP</sub> = +25 °C	P <sub>T</sub>	800	mW

- Notes:**
1. Derate linearly 2.30 mW /°C above T<sub>A</sub> = +25°C.
  2. T<sub>A</sub> = +55°C for UB on printed circuit board (PCB), PCB = FR4 .0625 inch (1.59 mm) 1 - layer 1 Oz Cu, horizontal, still air, pads (UB) = .034 inch (0.86 mm) x .048 inch (1.22 mm), R<sub>θJA</sub> with a defined thermal resistance condition included is measured at P<sub>T</sub> = 400 mW .



**UB Package**

Also available in:

**TO-46 (TO-206AB)**

(axial leaded)

 [2N2944A – 2N2946A](#)

#### **MSC – Lawrence**

6 Lake Street,  
Lawrence, MA 01841  
Tel: 1-800-446-1158 or  
(978) 620-2600  
Fax: (978) 689-0803

#### **MSC – Ireland**

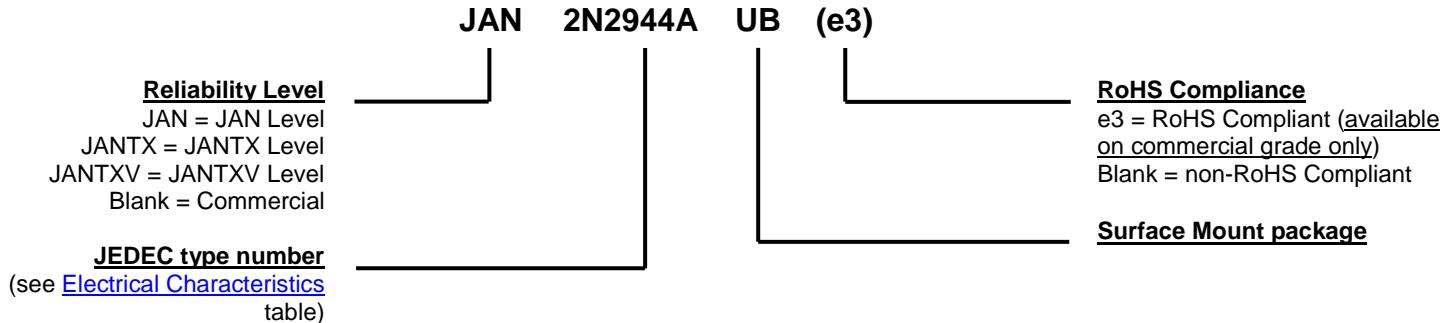
Gort Road Business Park,  
Ennis, Co. Clare, Ireland  
Tel: +353 (0) 65 6840044  
Fax: +353 (0) 65 6822298

#### **Website:**

[www.microsemi.com](http://www.microsemi.com)

**MECHANICAL and PACKAGING**

- CASE: Ceramic.
- TERMINALS: Gold plating over nickel under-plate. RoHS compliant matte/tin available on commercial grade only.
- MARKING: Part number, date code, manufacturer's ID.
- TAPE & REEL option: Standard per EIA-418D. Consult factory for quantities.
- WEIGHT: < 0.04 Grams.
- See [Package Dimensions](#) on last page.

**PART NOMENCLATURE**

**SYMBOLS & DEFINITIONS**

Symbol	Definition
$I_B$	Base current (dc).
$I_E$	Emitter current (dc).
$V_{CB}$	Collector to base voltage (dc).
$V_{EB}$	Emitter to base voltage (dc).
$V_{(BR)}$	Minimum Breakdown Voltage: The minimum voltage the device will exhibit at a specified current.

**ELECTRICAL CHARACTERISTICS @ 25 °C unless otherwise noted.**

Characteristic	Symbol	Min.	Max.	Unit
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**OFF CHARACTERISTICS:**

Collector-Emitter Breakdown Voltage $I_C = -10 \mu A$	2N2944AUB 2N2945AUB 2N2946AUB	V(BR)CEO	-10 -20 -35		V
Emitter-Collector Breakdown Voltage $I_E = -10 \mu A, I_B = 0$	2N2944AUB 2N2945AUB 2N2946AUB	V(BR)ECO	-10 -20 -35		V
Collector-Base Cutoff Current $V_{CB} = -15 V$	2N2944AUB	$I_{CBO}$	10		$\mu A$
$V_{CB} = -25 V$	2N2945AUB		10		
$V_{CB} = -40 V$	2N2946AUB		10		
Emitter-Base Cutoff Current $V_{EB} = -12 V$	2N2944AUB	$I_{EBO}$		-0.1	$\eta A$
$V_{EB} = -20 V$	2N2945AUB			-0.2	
$V_{EB} = -32 V$	2N2946AUB			-0.5	

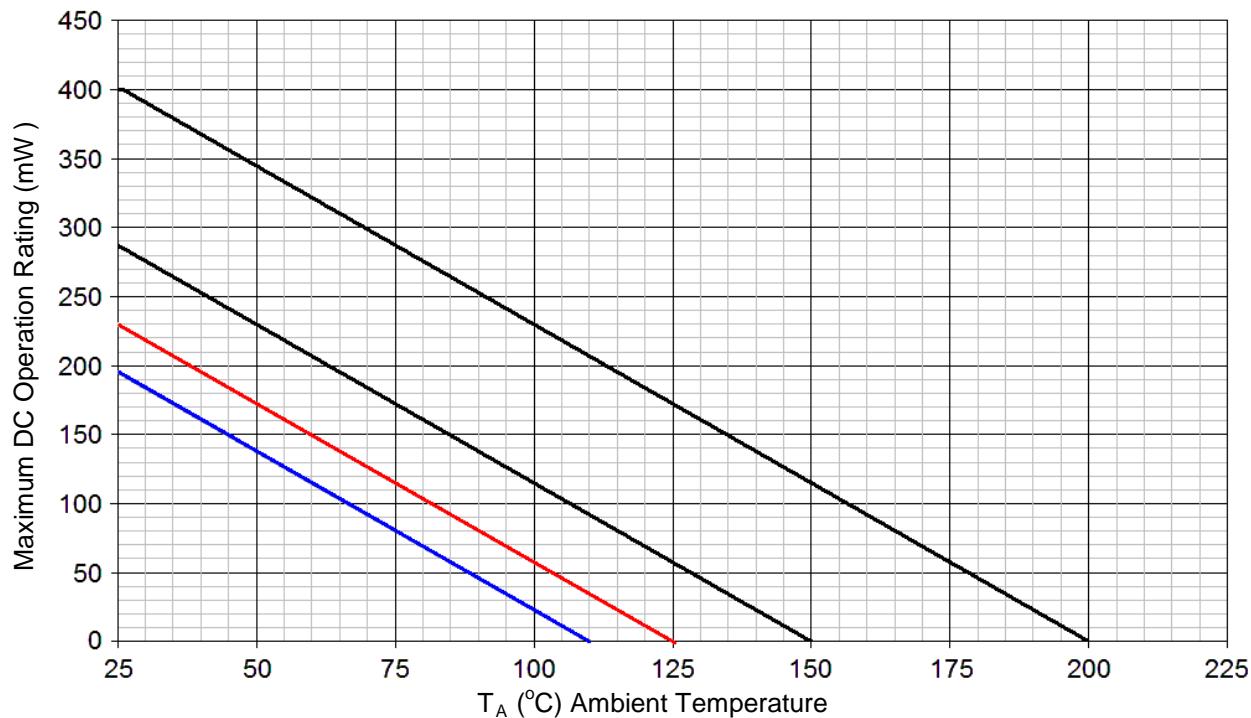
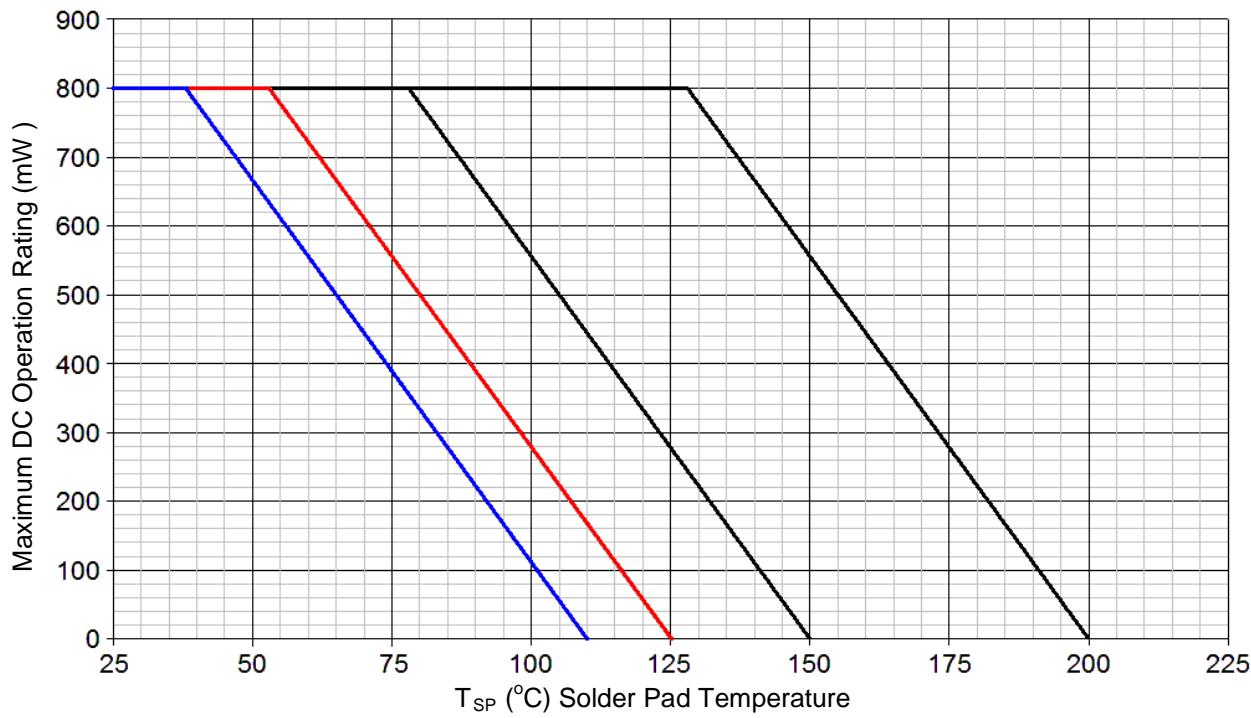
**ON CHARACTERISTICS: <sup>(1)</sup>**

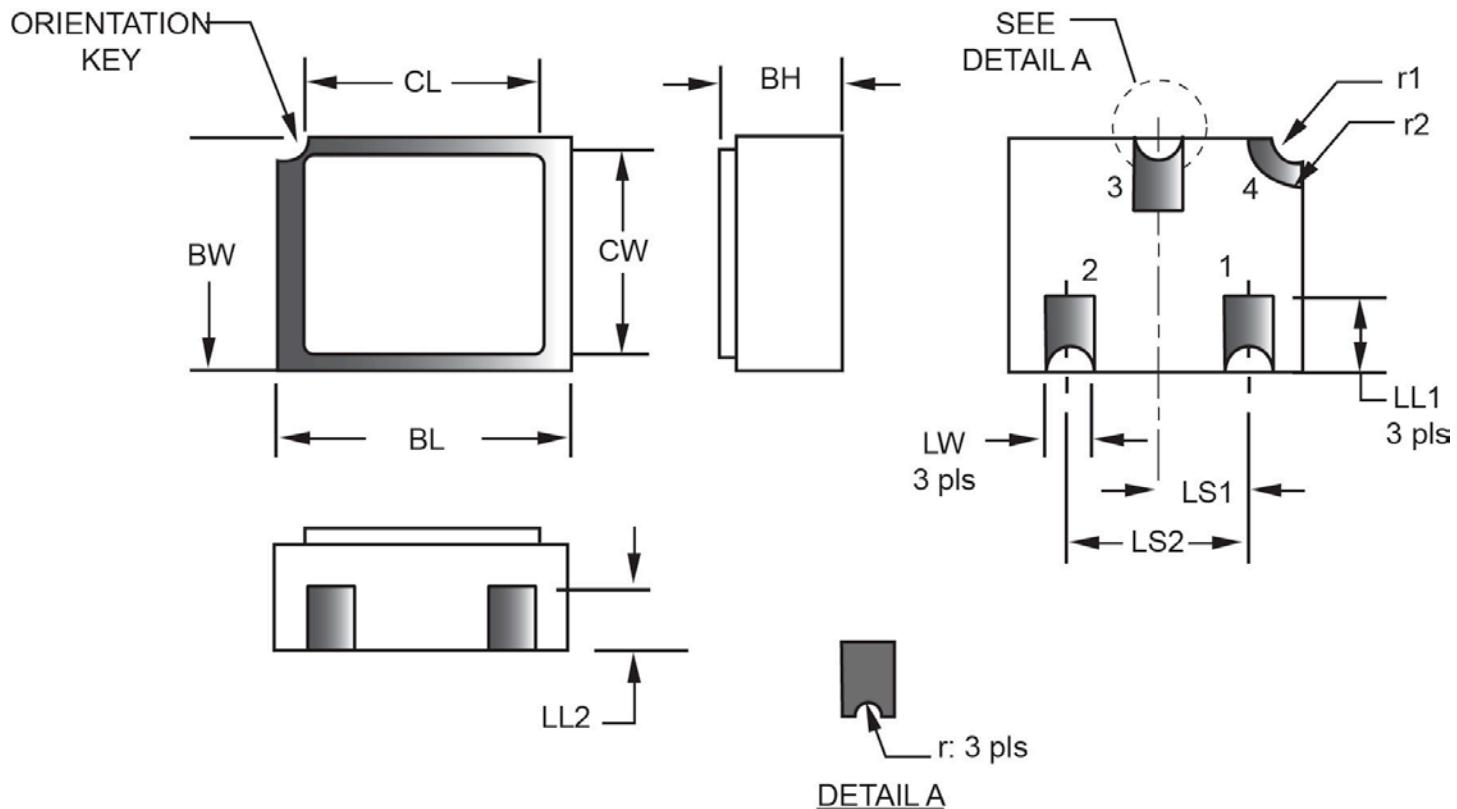
Forward-Current Transfer Ratio $I_C = -1.0 mA, V_{CE} = -0.5 V$	2N2944AUB 2N2945AUB 2N2946AUB	$h_{FE}$	100 70 50		
Forward-Current Transfer Ratio (inverted connection) $I_E = -200 \mu A, V_{EC} = -0.5 V$	2N2944AUB 2N2945AUB 2N2946AUB	$h_{FE(inv)}$	50 30 20		
Emitter-Collector Offset Voltage $I_B = -200 \mu A, I_E = 0$	2N2944AUB 2N2945AUB 2N2946AUB	$V_{EC(ofs)}$		-0.3 -0.5 -0.8	$mV$
$I_B = -1.0 mA, I_E = 0$	2N2944AUB 2N2945AUB 2N2946AUB			-0.6 -1.0 -2.0	
$I_B = -2.0 mA, I_E = 0$	2N2944AUB 2N2945AUB 2N2946AUB			-1.0 -1.6 -2.5	

**DYNAMIC CHARACTERISTICS:**

Emitter-Collector On-State Resistance $I_B = -100 \mu A, I_E = 0, I_e = 100 \mu A \text{ ac (rms)}$ $f = 1.0 \text{ kHz}$	2N2944AUB 2N2945AUB 2N2946AUB	$r_{ec(on)}$	10 12 14		$\Omega$
$I_B = -1.0 mA, I_E = 0, I_e = 100 \mu A \text{ ac (rms)}$ $f = 1.0 \text{ kHz}$	2N2944AUB 2N2945AUB 2N2946AUB		4.0 6.0 8.0		
Magnitude of Small-Signal Forward Current Transfer Ratio $I_C = -1.0 mA, V_{CE} = -6.0V, f = 1.0 \text{ MHz}$	2N2944AUB 2N2945AUB 2N2946AUB	$ h_{fel} $	15 10 5.0	55 55 55	
Output Capacitance $V_{CB} = -6.0 V, I_E = 0, 100 \text{ kHz} \leq f \leq 1.0 \text{ MHz}$		$C_{obo}$		10	$pF$
Input Capacitance $V_{EB} = -6.0 V, I_C = 0, 100 \text{ kHz} \leq f \leq 1.0 \text{ MHz}$		$C_{ibo}$		6.0	$pF$

(1) Pulse Test: Pulse Width = 300 s, duty cycle 2.0%.

**GRAPHS**

**FIGURE 1 – Temperature-Power Derating Curve ( $R_{\theta JA}$ )**

**FIGURE 2 – Temperature-Power Derating Curve ( $R_{\theta JSP}$ )**

**PACKAGE DIMENSIONS**

DETAIL A

Symbol	Dimensions				Note	Symbol	Dimensions				Note			
	inch		millimeters				inch		millimeters					
	Min	Max	Min	Max			Min	Max	Min	Max				
BH	.046	.056	1.17	1.42		LS1	.035	.039	0.89	0.99				
BL	.115	.128	2.92	3.25		LS2	.071	.079	1.80	2.01				
BW	.085	.108	2.16	2.74		LW	0.16	0.24	0.41	0.61				
CL		.128		3.25		r		.008		0.20				
CW		.108		2.74		r1		.012		0.31				
LL1	.022	.038	0.56	0.97		r2		.022		.056				
LL2	.017	.035	0.43	0.89										

**NOTES:**

1. Dimensions are in inches.
2. Millimeters are given for general information only.
3. Hatched areas on package denote metallized areas.
4. Pad 1 = Base, Pad 2 = Emitter, Pad 3 = Collector, Pad 4 = Shielding connected to the lid.
5. In accordance with ASME Y14.5M, diameters are equivalent to  $\Phi x$  symbology.